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- 3. (Amended) A process according to claim 1, wherein the degree of contamination is measured with the help of one or several oscillators which react to a change in its surface mass by changing resonance frequency.
- 4. (Amended) A process according to claim 1, wherein the degree of contamination is determined by reflectivity measurements.
- 5. (Amended) A process according to claim 1, wherein the degree of contamination is determined ellipsometrically.
- 6. (Amended) A process according to claim 1, wherein the degree of contamination is determined by measuring a stream of photons.
- 7. (Amended) A process according to claims 1, wherein the degree of contamination is determined while oxygen is being supplied.
- 8. (Amended) A process according to claim 1, wherein a precise threshold value is given, whereby exceeding the threshold value results in oxygen in a partial pressure range between 1×10^{-10} mbar to 1×10^{-3} mbar being added, and in the event that the threshold is not reached, the supply of oxygen being stopped.
- 9. (Amended) A device for in-situ decontamination of optical elements in an EUV lithography device, comprising: at least one measuring device to measure a degree of contamination of the optical element(s) and a connected control unit, which is connected to a device to supply O₂ to the EUV lithography device, and which is set up to compare the measured degree of contamination with at least one pre-set threshold value, and to control the supply of oxygen in relation to the corresponding comparison results.

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- 10. (Amended) A device according to claim 9, wherein the device has at least one light source for radiation in the wave length range between 150 nm and 300 nm.
- 11. (Amended) A device according to claim 9, wherein at least one measuring device has at least one quartz crystal microwave set up inside the lithography device.
- 12. (Amended) A device according to claim 9, wherein the measuring device has at least one additional light source and at least one detector, which are set up within the lithography device.
- 13. (Amended) A device according to claim 12, wherein a polarizer is set up in the beam path of at least one light source, near the light source, and an analyzer is set up near the detector.
- 14. (Amended) A device according to claim 9, wherein the measuring device has the means to measure a stream of photons that are connected to an optical element in the EUV lithography device.
- 15. (Amended) A device according to claims 9, wherein a measuring device connected to the control unit is set up as a residual gas-measuring device.